PCN Number: 20150603000 PCN Date: 06/08/2015								
Title: Qualification of GTBF as Additional Assembly/Test Site for Select Devices								
Customer Contact: PCN Manager Dept: Quality Services								
Proposed 1 st Ship Date: 09/08/		Estimated Sample			Date Provided at Sample request			
Change Type:								
Assembly Site			De	esign		Wafer Bump Site		
Assembly Process				-			Wafer Bump Material	
Assembly Materials							Wafer Bump Process	
Mechanical Specificat				Test Site		$\underline{\square}$	Wafer Fab Site	
Packing/Shipping/Lal	beling]		Ie	est Process	\underline{H}	Wafer Fab Materials	
				DC	N Details		Wafer Fab Process	
Description of Change:				F C				
Qualification of GTBF as additional assembly and test site for Select Devices. Assembly differences are shown in the following table: Group 1 Device:								
Manual Canada and					FME		GTBF	
Mount Compound Mold Compound					# MC-05 # R-12		SID# EY0000006 SID# EN0000038	
				עוכ	# K-12		SID# EN0000038	
Group 2 Device:		1			EME		CTRE	
Maxim Campanya d			NFME			GTBF		
Mount Compound Mold Compound			SID# MC-05			SID# EY0000006 SID# EN0000038		
Wire type			SID# R-12 Au			Cu		
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ. Reason for Change:								
Continuity of Supply								
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):								
None								
Changes to product identification resulting from this PCN:								
Assembly Site NFME Assembly Site Origin (22L) ASO: NFM GTBF (Great Team Backend Foundry) Assembly Site Origin (22L) ASO: GTF Sample product shipping label (not actual product label) (1P) SN74LS07NSR (a) 2000 (D) 0336 MADE IN: Malaysia G4 (a) 2000 (D) 0336 (31T) LOT: 3959047MLA MSL '2 /260C/1 YEAR SEAL DT 39 (b) TEXAS (L) T0: 1750 (c) 2000 (D) 033317 OPT: 39 (c) COOL (SSO: SHE (21L) CCO:USA (22L) ASO: MLA (22L) AS								
ASSEMBLY SITE CODES: NFME = E, GTBF = TBD								

Group 1 Product Affected:					
UA78M05CKCS	UA78M08CKCS	UA78M33CKCS			
UA78M05CKCSE3	UA78M08CKCSE3	UA78M33CKCSE3			
UA78M05IKCS	UA78M12CKCS				
UA78M05IKCSE3	UA78M12CKCSE3				
Group 2 Product Affected:					
LM317KCSE3					
	UA78M05CKCS UA78M05CKCSE3 UA78M05IKCS UA78M05IKCSE3 ected:	UA78M05CKCS UA78M08CKCS UA78M05CKCSE3 UA78M08CKCSE3 UA78M05CKCSE3 UA78M08CKCSE3 UA78M05IKCS UA78M12CKCS UA78M05IKCSE3 UA78M12CKCSE3 Gected: UA78M12CKCSE3	UA78M05CKCS UA78M08CKCS UA78M33CKCS UA78M05CKCSE3 UA78M08CKCSE3 UA78M33CKCSE3 UA78M05IKCS UA78M12CKCS UA78M05IKCSE3 UA78M05IKCSE3 UA78M12CKCSE3 UA78M05IKCSE3		

Qualification Report Qualify GTBF as subcon A/T site for 3pin TO-220 KCS PWR Packages

Product Attributes

Attributes	Qual Device: LM317KCS
Assembly Site	GTBF
Package Family	TO-220
Flammability Rating	UL-V94-0
Wafer Fab Supplier	SFAB
Wafer Fab Process	JI1

- QBS: Qual By Similarity

- Qual Device LM317KCS is qualified at Not Classified

Qualification Results

Data Display	cu a	s: Number of lots	/ Total Sam	
lama / Condition			uration	

Туре	Test Name / Condition	Duration	Qual Device: LM317KCS
AC	Autoclave 121C	96 Hours	3/237/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/255/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0
LI	Lead Fatigue	Leads	3/24/0
LI	Lead Pull to Destruction	Leads	3/24/0
MISC	Salt Atmosphere	Salt/Atmos	3/66/0
MQ	Manufacturability	(per mfg. Site specification)	3/Pass
PD	Physical Dimensions	(per mechanical drawing)	3/15/0
PKG	Lead Finish Adhesion	Leads	3/24/0
PKG	Solder Heat	10 sec	3/66/0
SD	Solderability	8 Hours Steam Age	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/273/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com